PDH0974A

100V N-Channel MOSFETs

General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDSON	ID
100V	6.2mΩ	100A

Features

- *100V,100A, RDS(ON) =6.2mΩ@VGS = 10V*
- *Improved dv/dt capability*
- *Fast switching*
- *Green Device Available*

TO263 Pin Configuration
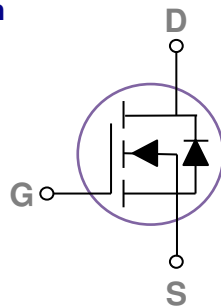
Applications

- *Networking*
- *Load Switch*
- *LED applications*
- *Quick Charger*

Absolute Maximum Ratings Tc=25℃ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	+20/-12	V
I_D	Drain Current – Continuous (T_C=25℃)	100	A
	Drain Current – Continuous (T_C=100℃)	63	A
I_{DM}	Drain Current – Pulsed[1]	400	A
P_D	Power Dissipation (T_C=25℃)	184	W
	Power Dissipation – Derate above 25℃	1.47	W/℃
T_{STG}	Storage Temperature Range	-50 to 150	℃
T_J	Operating Junction Temperature Range	-50 to 150	℃

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	℃/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	0.68	℃/W

Electrical Characteristics (T_J=25 ℃, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	100	---	---	V
I_{DSS}	Drain-Source Leakage Current	V_{DS}=100V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=80V , V_{GS}=0V , T_J=85℃	---	---	10	uA
I_{GSS}	Gate-Source Leakage Current	V_{GS}=20V , V_{DS}=0V	---	---	100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V , I_D=20A	---	5.4	6.2	mΩ
		V_{GS}=6V , I_D=10A	---	7.7	9.5	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	2	2.8	4	V
gfs	Forward Transconductance	V_{DS}=10V , I_D=3A	---	12	---	S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q_g	Total Gate Charge[2,3]	V_{DS}=80V , V_{GS}=10V , I_D=10A	---	57.9	110	nC
Q_{gs}	Gate-Source Charge[2,3]		---	10.8	20	
Q_{gd}	Gate-Drain Charge[2,3]		---	18.2	38	
$T_{d(on)}$	Turn-On Delay Time[2,3]	V_{DD}=50V , V_{GS}=10V , R_G=6Ω I_D=1A	---	24	48	ns
T_r	Rise Time[2,3]		---	19.8	39	
$T_{d(off)}$	Turn-Off Delay Time[2,3]		---	46	92	
T_f	Fall Time[2,3]		---	26	52	
C_{iss}	Input Capacitance	V_{DS}=50V , V_{GS}=0V , F=1MHz	---	3590	7180	pF
C_{oss}	Output Capacitance		---	590	1180	
C_{rss}	Reverse Transfer Capacitance		---	30	60	
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, F=1MHz	---	1.5	3	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	V_G=V_D=0V , Force Current	---	---	100	A
I_{SM}	Pulsed Source Current		---	---	200	A
V_{SD}	Diode Forward Voltage	V_{GS}=0V , I_S=1A , T_J=25℃	---	---	1	V
t_{rr}	Reverse Recovery Time	V_{GS}=0V,I_S=10A , di/dt=100A/μs	---	60	---	ns
Q_{rr}	Reverse Recovery Charge	T_J=25℃	---	117	---	nC

Note :
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%.
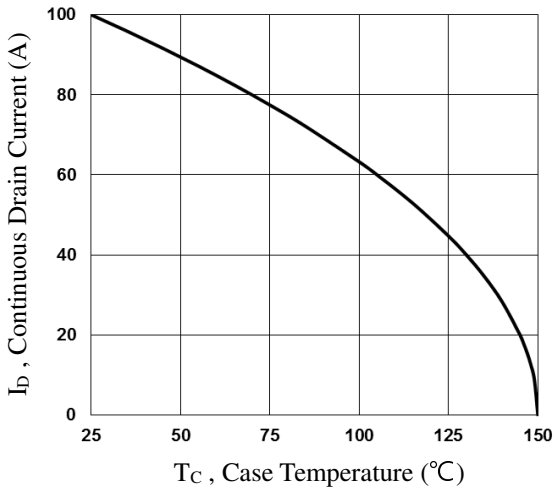3. Essentially independent of operating temperature.

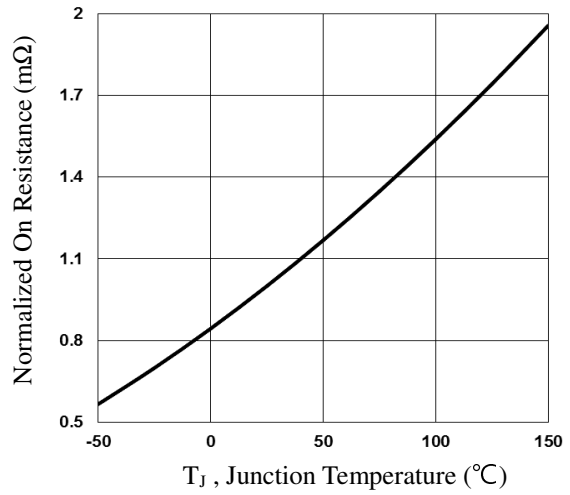Fig.1   Continuous Drain Current vs. T_C
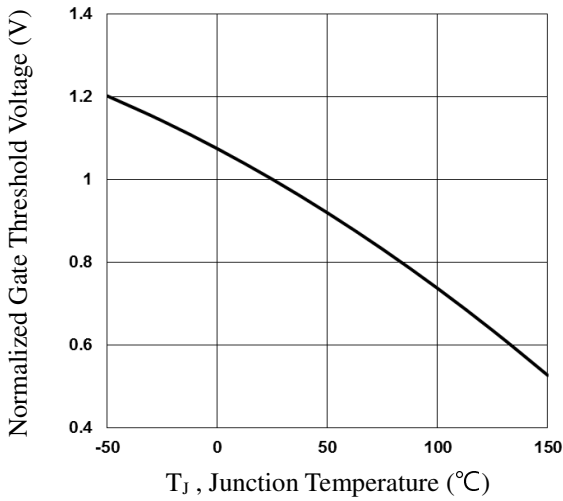

Fig.2   Normalized RDSON vs. T_J

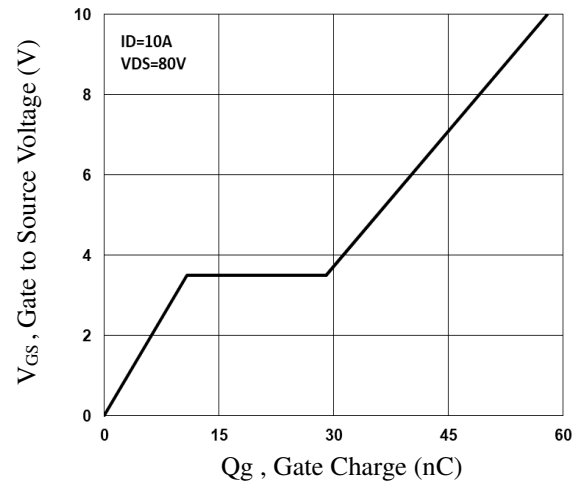Fig.3   Normalized Vth vs. T_J

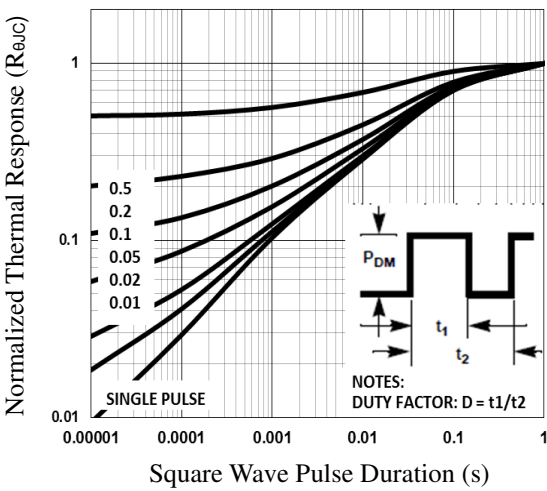Fig.4   Gate Charge Characteristics

Fig.5   Normalized Transient Impedance

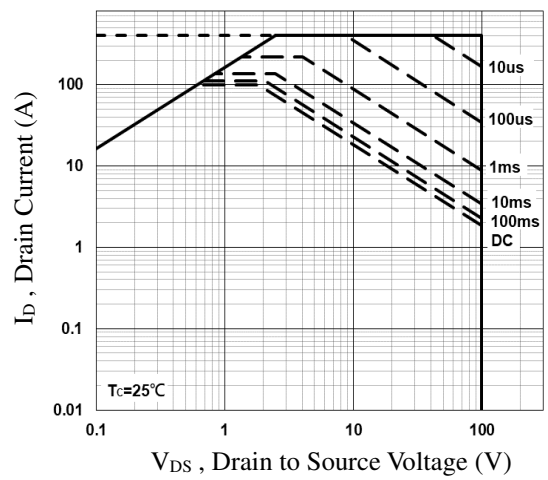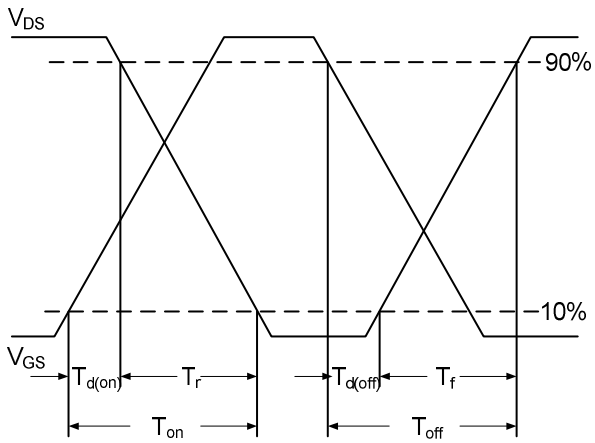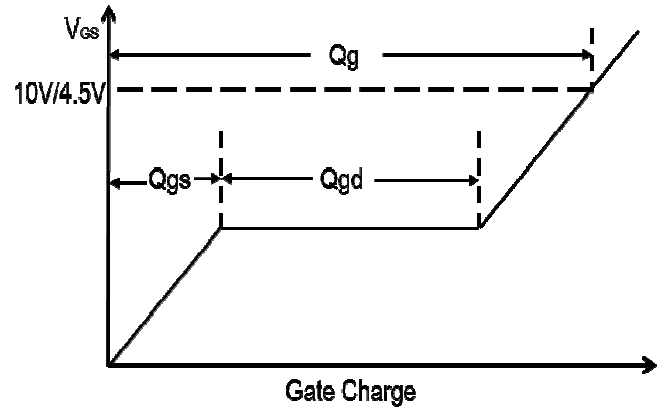Fig.6   Maximum Safe Operation Area

Fig.7   Switching Time Waveform

Fig.8   Gate Charge Waveform

TO263 PACKAGE INFORMATION